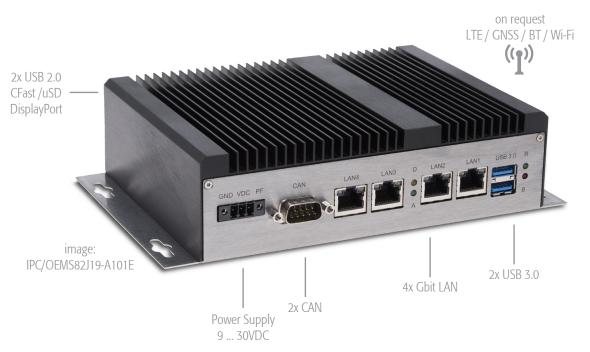
Embedded Box PCs COMPACT-S OEM Series

Industrial compact PC with Intel® Atom™ Elkhart Lake processor (x6000)



IPC/COMPACT82-OEM

This fanless COMPACT82-S OEM generation is based on the Intel[®] Atom[™] Elkhart Lake (EHL) processor technology and offers a wide range of interface options.

The robust and uncompromising industrial design allows the implementation in the most demanding applications and guarantees long term availability with Win10 IoT or Linux support.

- Multi-core 64-bit Intel[®] Atom[™] processor
- 24/7 continuous operation
- No moving parts
- Product lifecycle management
- Long term availability with fixed BOM







Product Highlights

Hardware Watchdog Temperature supervision Real time clock Trusted platform module (TPM 2.0) UEFI Secure Boot ESD- protection on all interfaces Aluminum / stainless steel housing No active cooling required Cable- and fanless design

Product Feature

Intel[®] Atom[™] Elkhart Lake, 4 cores RAM soldered on board up to 16GB LPDDR4 Socket for CFast DisplayPort, Ethernet, USB3, CAN, Mini PCIe Up to 4K resolution

Industries / Applications

AGV (Automated Guided Vehicle) Industrial Automation Traffic control Cleantech

preliminary

Order Code IPC/OEMS82J19-A101E¹ IPC/OEMS82H15-A102E¹ IPC/OEMS82J19-A103E¹

	Order Code	IPQ/UEIVIS82J19-ATUTE	IPC/UEI/IS82H15-A102E	IPQ/UEIVIS8ZJ19-ATU3
Processor / Performance				
Intel® Atom™ x6425RE - Quad core 1.9GHz clock 16GB RAM		•	on request	•
ntel® Atom™ x6414RE - Quad core 1.5GHz clock 4GB RAM		on request	•	on request
Memory / Storage				
L2 cache		1.5MB	1.5MB	1.5MB
.PDDR4x (3200 MT/s) RAM		16GB	4GB	16GB
CFast socket		1	1	1
MicroSD card socket ²		1	1	1
Features				
Real time clock (RTC) with battery backup		•	•	•
Multistage Watchdog		•	•	•
Temperature supervisor		•	•	•
TPM 2.0 according to ISO/IEC11889		•	•	•
DisplayPort 1.2 (DDI) up to 4096×2160@60Hz (4K)		1	1	1
USB version 3.1 (front)	(Type A)	2	2	2
JSB version 2.0 (back)	(Type A)	2	none	none
JSB version 2.0 ³ (shared one with mPCIE)	(турс А)	2	none	2
Ethernet 10/100/1000 BASE-T (1x Intel® GbE 3x Intel® I210-IT)	(RJ45)	4	2	4
RS232 Serial Interface (RX, TX, RTS, CTS) ³	(נדטו)	1	none	1
CAN (PEAK, SJA1000 compatible) isolated	(1x DSUB9)	2	none	none
ntel CAN-FD	(1x DSUB9)	none	none	1
Vini PCIe socket with miniSIM ³	(17.05005)	1	1	1
Technical Data		,	,	1
Dimensions w174 x h52 x d127 mm (housing without mounting bracket)		•	•	•
Wall mounting (Accessories for DIN Rail Mounting not included in delivery. E.g. IPC/MKITCP-2G41 or I		•	•	•
Net weight [gram]	PC/MINITCP-2H)	~950	~950	~ 950
nput voltage 9 30VDC ⁴ non-isolated Fused and reverse polarity protected		•	• •	• 550
Power consumption typ. [Watt] @ 24V without Add-Ins		tbd	tbd	tbd
Shield and internal ground are separated (only capacitive connection	1)	i.Du		i.bu
Isolation between Electronics and Shield ($U = 50VDC$)		R ≥50kOhm	R ≥50kOhm	R ≥50kOhm
Environmental Conditions		R ESORONIN	R ESOROHIM	K ESOKOIIII
Operating temperature (ambient) ⁵		-40°C +70°C	-40°C +70°C	-40°C +70°C
Non operating temperature (Recommended storage temperature 20°C 25°C)		-40°C +85°C	-40°C +85°C	-40°C +85°C
Protection standard		IP40	IP40	IP40
Conformal coating 6		on request	on request	on request
bhock: designed to meet EN60068-2-27		on request	on request	on request
/ibration: designed to meet EN60068-2-6		•	•	•
EMC according to EN-55032/55035		•	•	•
Safety designed to meet IEC/EN62368		•	•	•
Radio and Telecommunication: Designed to meet RED		•	•	•
MTBF ~ 550 000h @ 25°C ambient acc. to Telcordia SR-332, Environment GB, excluding battery		tbd	tbd	tbd
	Dallery	ωu	wu	
Optional enhancement cards		on rossist	on rossist	op vorst
Wireless Module (5G, LTE / GNSS / BT / WiFi) 1		on request	on request	on request

¹Please contact factory for minimum order quantities

² The Intel processor chipset contains several issues in SD and SDIO Hostcontroller. Please check Intel ERRATA for additional information

³ Internal connector

⁴ mating type Weidmüller BCZ 3.81/03/180F SN BK BX (1792960000) - included in scope of delivery

⁵ Maximum ambient temperature is highly dependent on installation situation, air flow, interface connection and CPU/GPU load. Please see user documentation.

⁶ on all possible components (excl. Connectors and wireless devices)

Product specifications subject to change without notice. | All data is for information purposes only and not guaranteed for legal purposes. Information in this data sheet has been carefully checked and is believed to be accurate. However, no responsibility is assumed for inaccuracies. Please refer to the user documentation for additional product specification.

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